

April 27 Barrel Electronics Video Conference.

Agenda Items:

- Board status
- Work in SR
- Work at PENN
- Miscellaneous issues

Board Status:

AR2F: We received about a third of the production order (25 boards) from ACAMAS on Friday. Bjorn is here to test them, and he has gone through all 25. 7 need to go for re-work but the majority of those have non-soldering related problems (mostly bad chips). The rest of the boards are supposed to arrive at the end of the week.

AR3F: ACAMAS is predicting that the pre-series will be sent on May 5<sup>th</sup>.

ACAMAS has had trouble with the 2F and 3F boards, because some subtle issue in the way that Björn layed out the traces is causing the small 402 package resistors to flip up on one end while being heated in the oven. ACAMAS is sending us examples so that we can avoid this in the future.

Work in SR:

Björn is here this week to help out testing the AR2F boards. See the above item for the report on that. At the same time, Chuck has been installing AR3B boards on the barrel. This is going smoothly, with no problems to report. The AR3B boards have, whenever possible, been matched with certain modules in order to minimize the number of dead channels (by matching boards and modules in such a way that dead channels on boards get matched with straws that are already dead). We have found 16 such matches for all of AR3B.

Work at PENN:

The type-3 section of the first front harness has been verified and the other part is still being worked on. Mitch mentions that having some shorted backend cables would make that effort easier at PENN and it is agreed that some of the cables from the test beam should be sent to PENN for this purpose. People at PENN have been having an extremely hard time getting clean ROD fine delay scans with the 100 meter cables that they have. The TTC scans are fine.